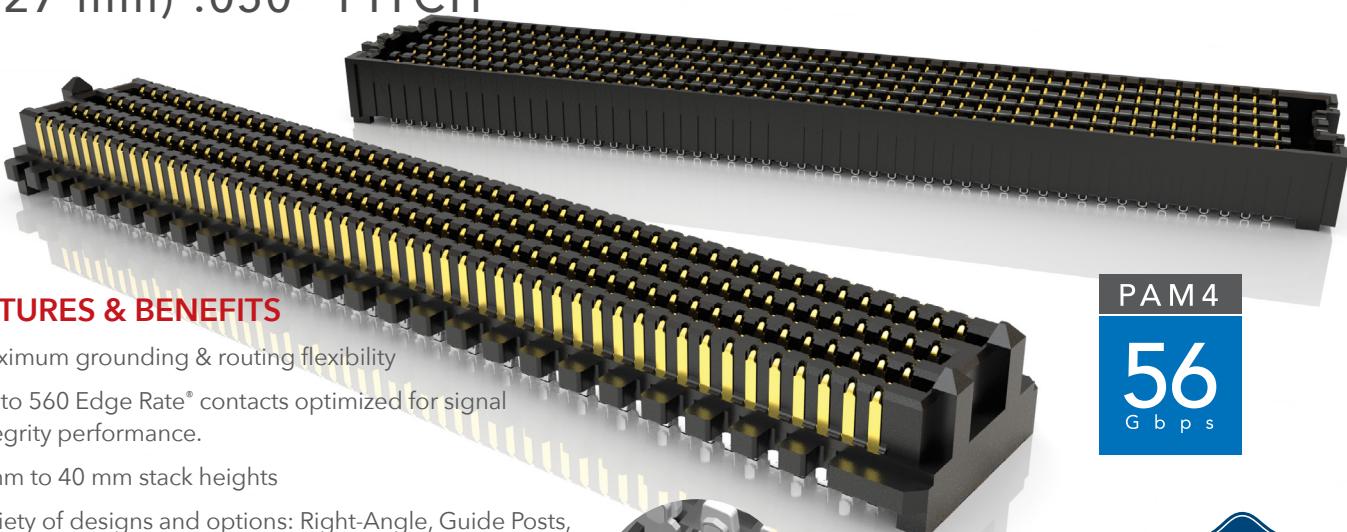


# SEARRAY™

## HIGH-DENSITY OPEN-PIN-FIELD ARRAYS

(1.27 mm) .050" PITCH



### FEATURES & BENEFITS

- Maximum grounding & routing flexibility
- Up to 560 Edge Rate® contacts optimized for signal integrity performance.
- 7 mm to 40 mm stack heights
- Variety of designs and options: Right-Angle, Guide Posts, 85 Ω Elevated Risers, 85 Ω Tuned, Press-Fit and Press-Fit Right-Angle, Guide Post Field Termination Kits
- Cable mates (SEAC Series) and Jack Screw Standoffs (JSO Series) also available
- Analog over Array™ capable
- Standards: VITA™ 47, VITA™ 57.1 FMC™, VITA™ 57.4 FMC™+, VITA™ 74 VNX™, PISMO™ 2
- Supports high-speed protocols such as Ethernet, PCI Express®, Fibre Channel & InfiniBand™
- Severe Environment Testing qualified (SEAM/SEAF); aligns with MIL-DTL-55302. Visit [samtec.com/set](http://samtec.com/set)

VITA/VNX/VNX+/FMC/FMC+/XMC/XMC+ are all respective trademarks of VITA PCI-SIG®.

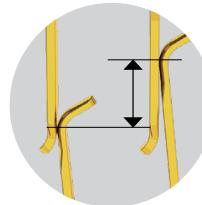
The PCI Express® design marks are registered trademarks and/or service marks of PCI-SIG.

PAM4  
56  
G b p s



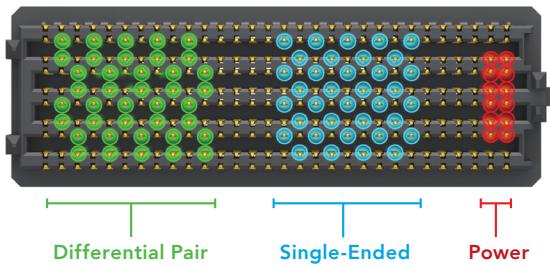
Solder Charges

EDGE RATE®  
CONTACT



(1.12 mm) .044"  
Nominal Wipe

### MAXIMUM GROUNDING & ROUTING FLEXIBILITY



Differential Pair

Single-Ended

Power

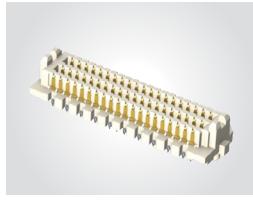
Series	Insulator Material	Contact Material	Plating	Operating Temp Range	Current Rating	Voltage Rating	Lead-Free Solderable
SEAM/SEAF	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	2.7 A (10 pins powered)	240 VAC/339 VDC	Yes
SEAM-RA/SEAF-RA	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.9 A (10 pins powered)	240 VAC/339 VDC	Yes
SEAM-GP	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	2.7 A (10 pins powered)	240 VAC/339 VDC	Yes
SEAMP/SEAPP	Natural High Temp Nylon	Copper Alloy (SEAMP) BeCu Alloy (SEAPP)	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.9 A (6 pins powered)	255 VAC/361 VDC	Not Available
SEAR	Black LCP	Hard Gold Plated	Au over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.4 A (20 pins powered)	240 VAC/339 VDC	Not Available
SEAMI	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	Not Available	Not Available	Yes

**Note:** Some lengths, styles and options are non-standard, non-returnable

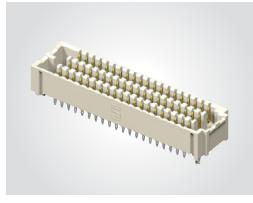
## (1.27 mm) .050" PITCH • PRESS-FIT & 85 Ω OPEN-PIN-FIELD ARRAYS

SERIES	POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	OPTION	PACKAGING
SEAMP Terminal	-10, -20, -30, -40, -50	-02.0 (SEAMP only)	-L = 10 $\mu$ " (0.25 $\mu$ m) Gold on contact area, Matte Tin on tail	-04, -06, -08, -10	-GP Guide Post (SEAMP only)	-TR = Tape & Reel
SEAFP Socket		-05.0 (SEAFP only)		SEAFP: -04 & -06 Rows only		-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

**SEAMP**  
Board Mates:  
SEAF,  
SEAF-RA-GP,  
SEAFP



**SEAFP**  
Board Mates:  
SEAM,  
SEAM-RA,  
SEAMP



Technical drawing of the SEAMP component showing dimensions: No. of positions x (1.27).050 + (5.18).204, A, (4.60).181, (1.78).070, and a side view showing height (1.78).070.

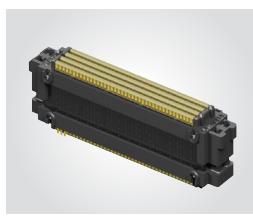
Technical drawing of the SEAFP component showing dimensions: No. of positions x (1.27).050 + (5.82).229, A, (5.00).197, (1.78).070, and a side view showing height (1.78).070.

NO. OF ROWS	A
-04	(7.06).278
-06	(9.60).378
-08	(12.14).478
-10	(14.68).578

View complete specifications at: [samtec.com?SEAMP](http://samtec.com?SEAMP) & [samtec.com?SEAFP](http://samtec.com?SEAFP). Visit [samtec.com?SEAFP-RA](http://samtec.com?SEAFP-RA) for right-angle socket.

SERIES	POSITIONS PER ROW	LEAD STYLE	NO. OF ROWS	085
SEAR 85 Ω Tuned Riser	-40, -50	-10.0 = 20 mm Mated Height -20.0 = 30 mm Mated Height -30.0 = 40 mm Mated Height	-06, -08, -10	
SEAR Board Mates: SEAFC				

**SEAR**  
Board Mates:  
SEAFC



Technical drawing of the SEAR component showing dimensions: A and B.

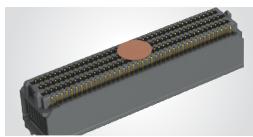
POSITIONS PER ROW	A
-40	(71.42).2812
-50	(84.12).3312

NO. OF ROWS	B
-06	(11.43).450
-08	(13.97).550
-10	(16.51).650

SERIES	POSITIONS PER ROW	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	K	"X"R
SEAMI 85 Ω Tuned Terminal	-40, -50	-L = 10 $\mu$ " (0.25 $\mu$ m) Gold on contact area, Matte Tin on solder tail	-08 -10	-1 = Tin/Lead Alloy Solder Charge -2 = Lead-Free Solder Charge			
SEAMI Board Mates: SEAF							

**SEAMI**  
Board Mates:  
SEAF

**Note:** Some lengths,  
styles and options  
are non-standard,  
non-returnable



Technical drawing of the SEAMI component showing dimensions: No. of positions x (1.27).050 + (4.98).196, A, (14.66).577, and a side view showing height (14.66).577.

Technical drawing of the SEAF component showing dimensions: No. of positions x (1.27).050 + (5.18).204, A, (4.60).181, (1.78).070, and a side view showing height (1.78).070.

NO. OF ROWS	A
-08	(13.41).528
-10	(15.95).628

View complete specifications at: [samtec.com?SEAR](http://samtec.com?SEAR) & [samtec.com?SEAMI](http://samtec.com?SEAMI).